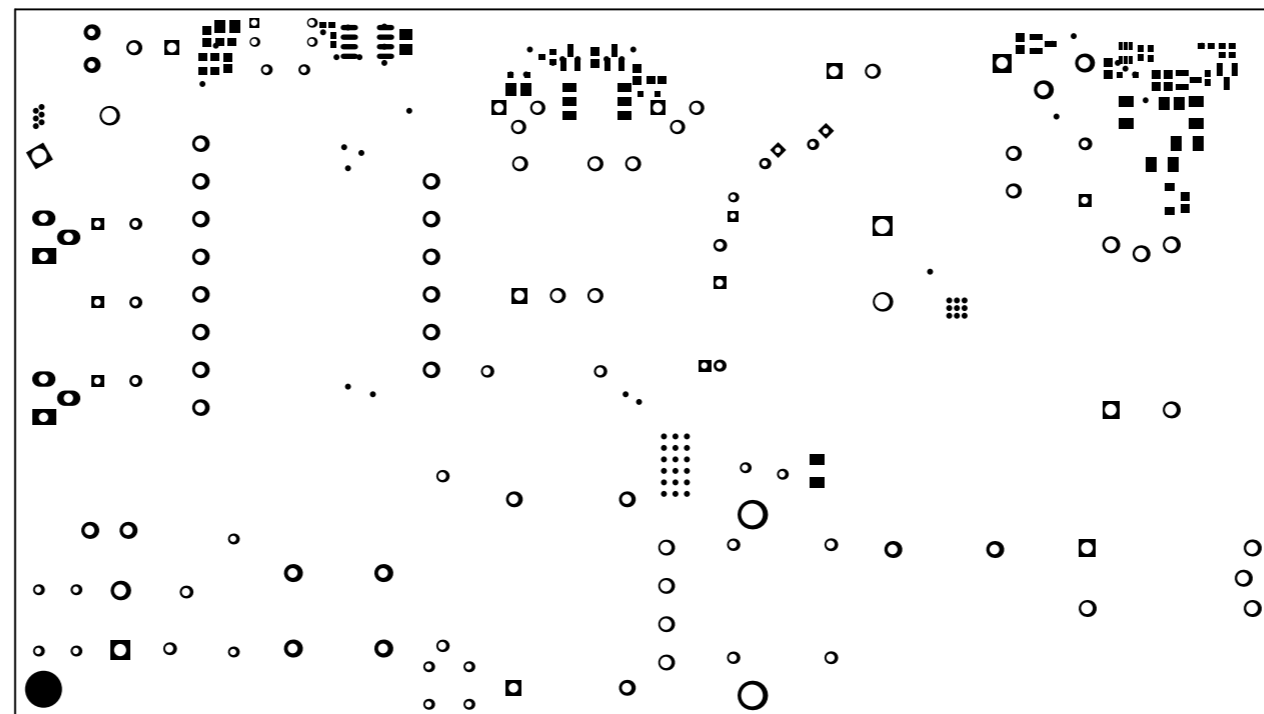
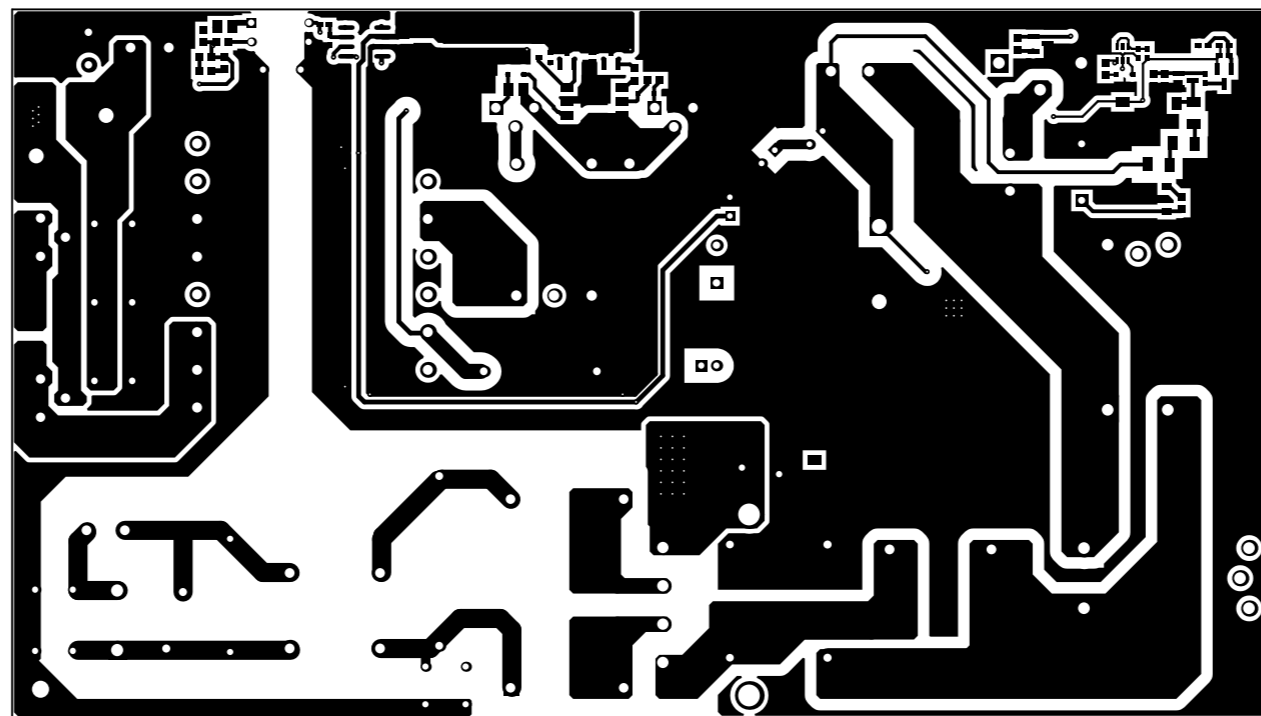


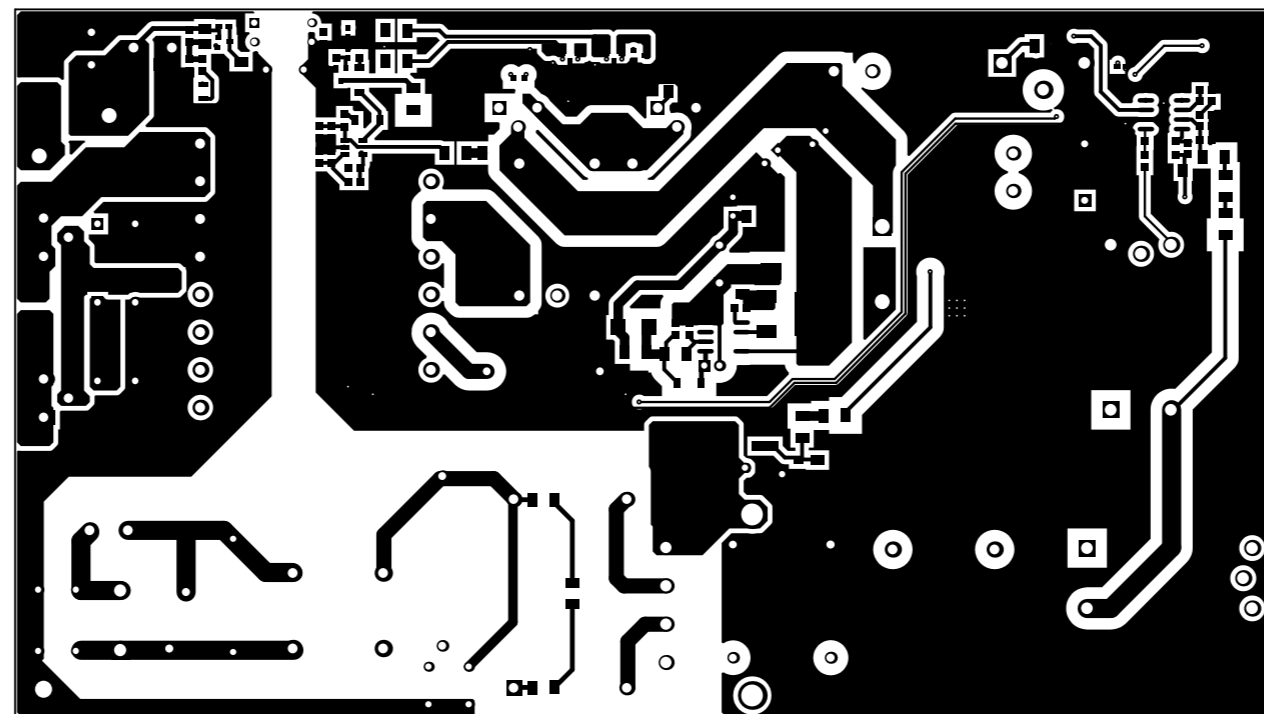
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/16/2014 10:11:44 PM	TEXAS INSTRUMENTS	



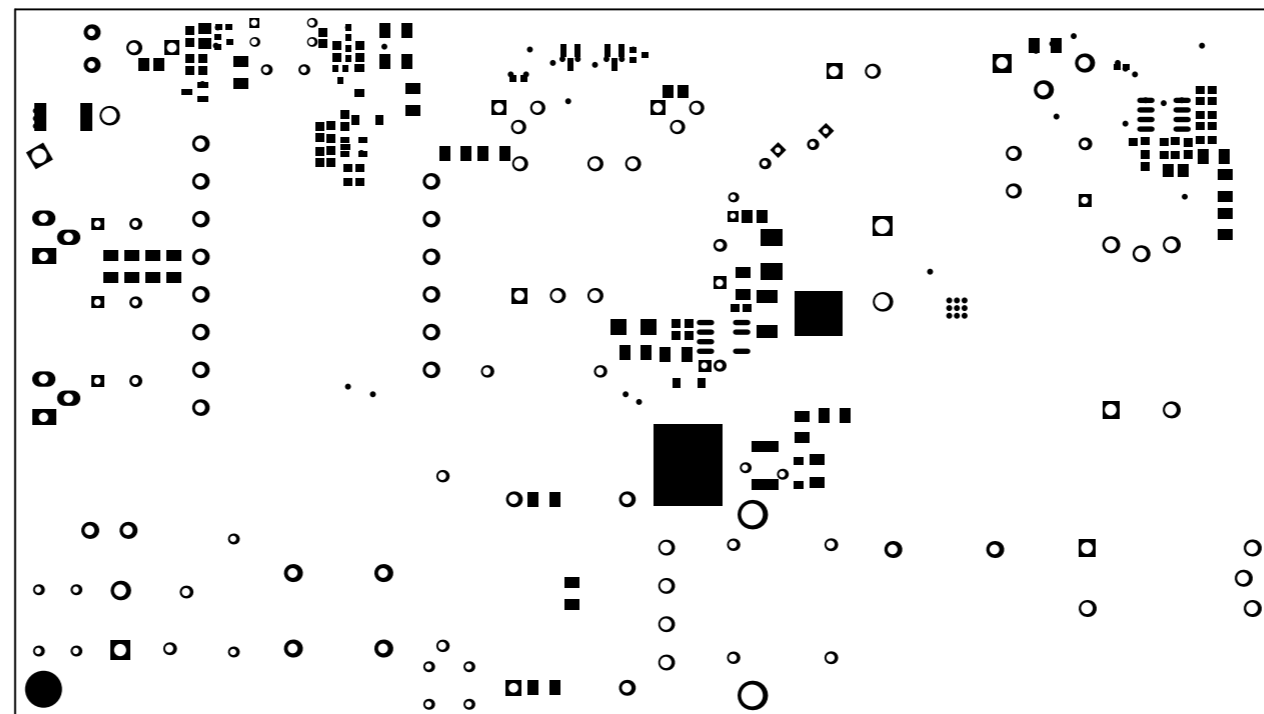
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/16/2014 10:11:45 PM	TEXAS INSTRUMENTS	



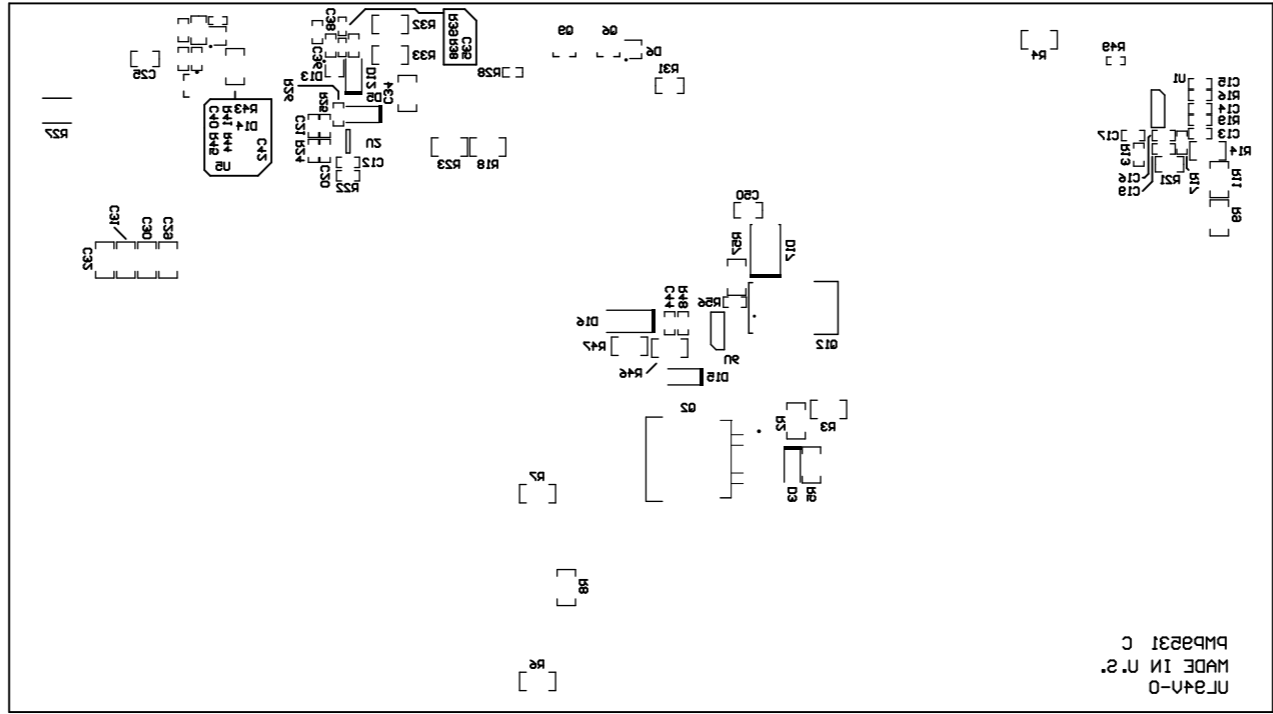
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/16/2014 10:11:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/16/2014 10:11:46 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/16/2014 10:11:47 PM	TEXAS INSTRUMENTS	

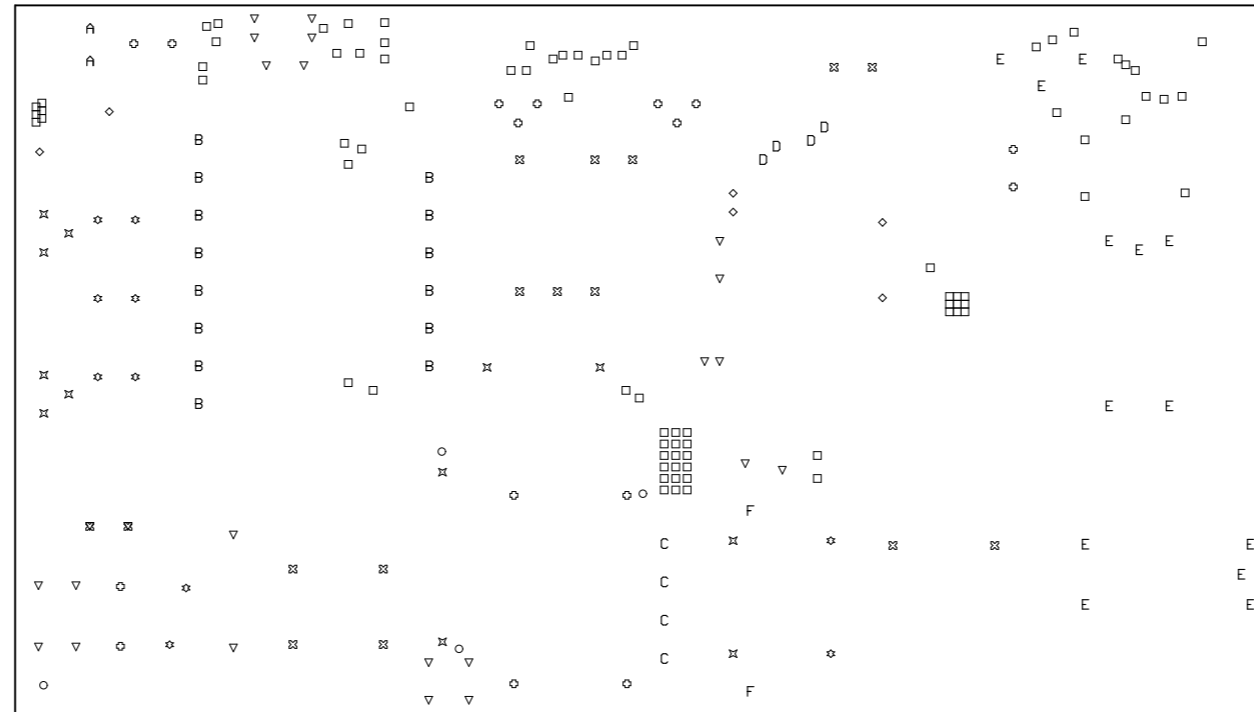


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/16/2014 10:11:47 PM	TEXAS INSTRUMENTS	

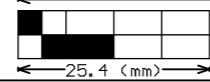
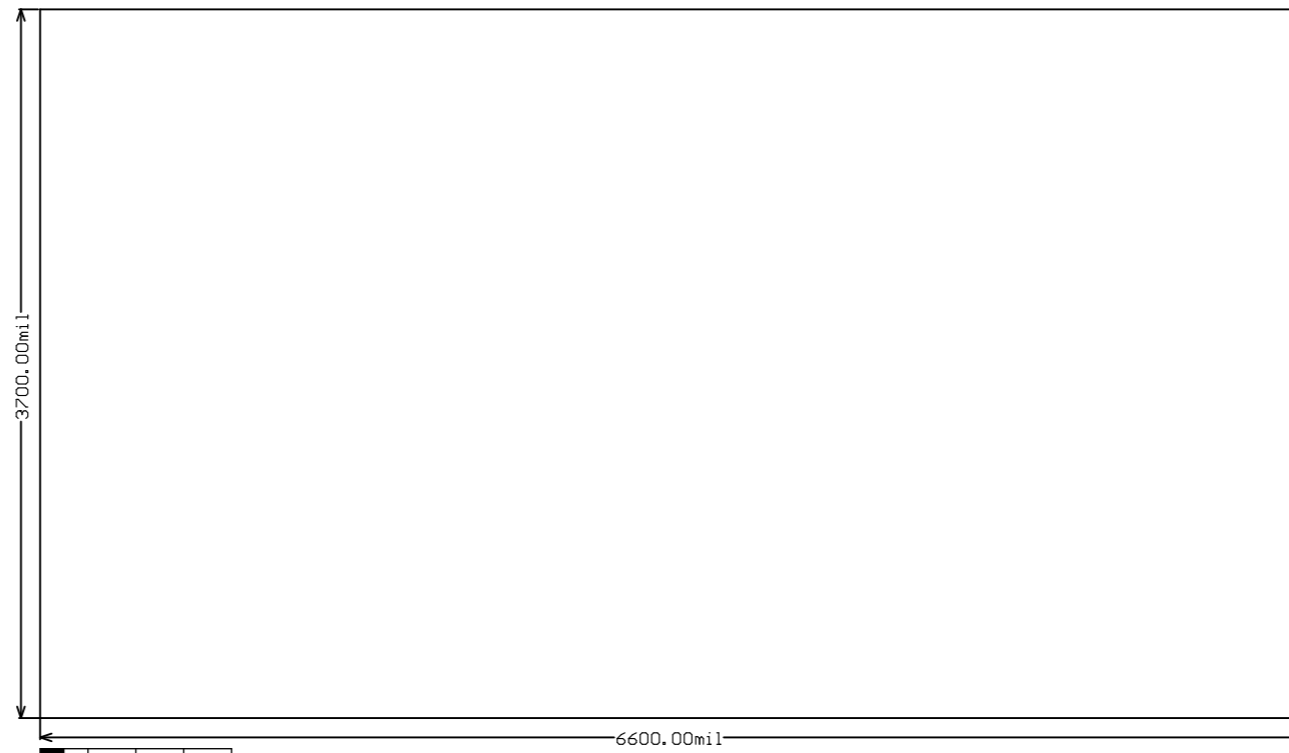
Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
□	80	10mil (0.254mm)			PTH	Round
◇	2	29.528mil (0.75mm)			PTH	Round
D	4	31mil (0.787mm)			PTH	Round
▽	20	33.465mil (0.85mm)			PTH	Round
☆	6	35.433mil (0.9mm)			PTH	Round
□	2	37.402mil (0.95mm)			PTH	Round
▽	4	39.37mil (1mm)			PTH	Round
A	2	40mil (1.016mm)			PTH	Round
⊗	6	41.339mil (1.05mm)			PTH	Round
☆	4	43.307mil (1.1mm)			PTH	Round
⊗	6	50mil (1.27mm)			PTH	Round
○	14	51.181mil (1.3mm)			PTH	Round
⊗	8	52mil (1.321mm)			PTH	Round
B	14	53.15mil (1.35mm)			PTH	Round
⊗	8	55.118mil (1.4mm)			PTH	Round
C	4	59.055mil (1.5mm)			PTH	Round
E	13	62mil (1.575mm)			PTH	Round
○	2	64.961mil (1.65mm)			PTH	Round
◇	4	78.74mil (2mm)			PTH	Round
○	1	90mil (2.286mm)			PTH	Round
F	2	114.961mil (2.92mm)			PTH	Round
○	3	30mil (0.762mm)	300mil (7.62mm)	270mil (6.858mm)	PTH	Slot
	209 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/16/2014 10:11:48 PM	TEXAS INSTRUMENTS	



25.4 (mm)

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9531	REV: C	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/16/2014 10:11:52 PM	TEXAS INSTRUMENTS	

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